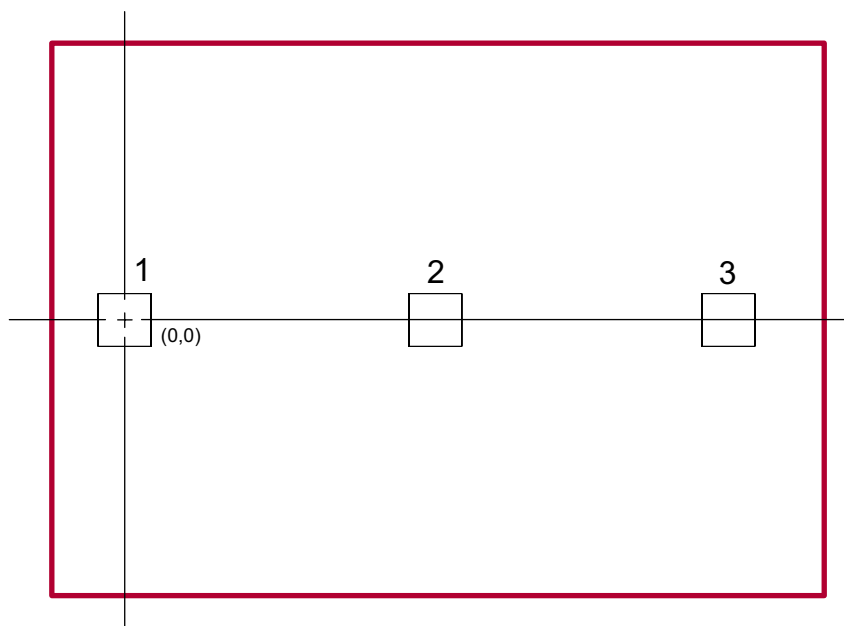


Pad Layout



Die Specifications

Die Dimensions (mils)			Die Dimensions (μm)			Back Side Metal	Back Side	Bonding Pad Material
Length ¹	Width ¹	Thickness ²	Length ¹	Width ¹	Thickness ²			
49.21	69.80	9.49 - 12.52	1250	1750	241 - 318	None	Drain	Al/Cu/Si

Pad Descriptions

Pad #	Function	x Position ² (μm)	y Position ² (μm)	x Size (μm)	y Size (μm)
1	Source	0	0	120	120
2	Gate	705	0	120	120
3	Drain	1370	0	120	120

Notes:

1. Maximum values.
2. Position referenced to center of pad.

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